

SPECIALTY PCB

CAPABILITIES

METAL SUBSTRATE PCB

Aluminum Substrate, Copper Subs, Aluminum Substrate and Copper Substrates

Metal-Substrate Control Depth Capability (mm)	±0.05
Counter Bore Depth-Controlled Capability (mm)	±0.10
Maximum Copper Weight (OZ)	12

SPECIAL PROCESSES

Heat Sink	Metal-Buried PCB	Hybrid Lamination
ViPPO	Embedded Resistance	Micro-Via Copper Fill
Resin Fill	Embedded Capacitance	Heavy Copper UL - 60oz
[Conductive and Non-Conductive]		Back Drill
Oversize Backplane		

SURFACE FINISHES

- HASL
- ENIG
- ENEPIG
- Immersion Silver
- Immersion Tin
- Electrolytic Nickel/Gold
- Wire Bondable Soft Gold
- OSP

MATERIALS

- Standard Tg FR-4
- Mid Tg FR-4
- High Tg FR-4
- Polyimide
- High Speed Materials
- Mixed Dielectric Constructions

CERTIFICATIONS

- UL
- ISO9001 (Quality System)
- ISO14001 (Environmental)
- OHSAS18001 (Safety)
- ISO27001 (IP Protection)

LEAD TIMES

Lead times vary widely depending on material selection and technology level. Lead time can be evaluated at time of quote.

